

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

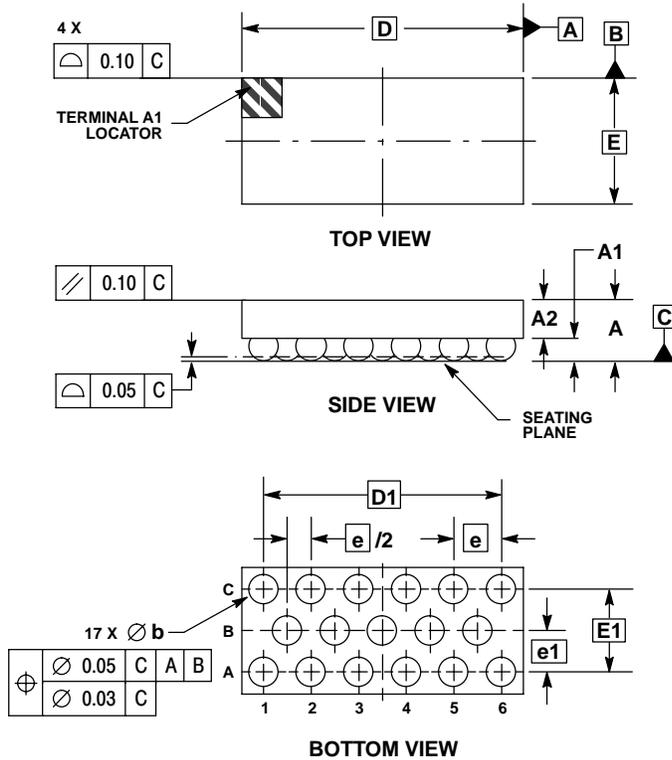


A1

SCALE 4:1

FLIP-CHIP-17 CSP CASE 499AD-01 ISSUE A

DATE 08 DEC 2005

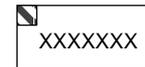


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.740
A1	0.250	0.310
A2	0.380	0.430
D	2.960 BSC	
E	1.330 BSC	
b	0.350	0.410
e	0.500 BSC	
e1	0.435 BSC	
D1	2.500 BSC	
E1	0.870 BSC	

GENERIC MARKING DIAGRAM*



XXXXXXX = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	FLIP-CHIP-17 CSP, 2.96x1.3 MM, 350 μm SPHERE	PAGE 1 OF 2

